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Details

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Product Status	Last Time Buy
Core Processor	C166SV2
Core Size	16-Bit
Speed	40MHz
Connectivity	CANbus, EBI/EMI, I ² C, SPI, UART/USART
Peripherals	PWM, WDT
Number of I/O	103
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	· ·
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 2.7V
Data Converters	A/D 16x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	-
Package / Case	
Supplier Device Package	
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc167ci32f40fbbafxqma1

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XC167CI-32F 16-Bit Single-Chip Microcontroller with C166SV2 Core

Microcontrollers



Never stop thinking



XC167 Revisio	n History: V1.1, 2006-08
Previous	s Version(s):
V1.0, 20	05-06
Page	Subjects (major changes since last revision)
13	Description of the TRST signal modified.
19	Footnote added about pins XTAL1/XTAL3 belonging to $V_{\rm DDI}$ power domain.
53	Instructions Set Summary improved.
60	Footnote added about amplitude at XTAL1 pin.
85	Green package added.
85	Thermal Resistance: R_{THA} replaced by $R_{\Theta \text{JC}}$ and $R_{\Theta \text{JL}}$ because R_{THA} strongly depends on the external system (PCB, environment). P_{DISS} removed, because no static parameter, but derived from thermal resistance.
	Title at the Cover Page corrected XC167CS to XC167CI.

We Listen to Your Comments

Any information within this document that you feel is wrong, unclear or missing at all? Your feedback will help us to continuously improve the quality of this document. Please send your proposal (including a reference to this document) to: mcdocu.comments@infineon.com



Table 2	Pi	n Definit	tions and F	unctions				
Sym- bol	Pin Num.	Input Outp.	Function					
P20.12	3	10	For details	, please refer to the description of P20 .				
NMI	4	1	Non-Maskable Interrupt Input. A high to low transition at this pin causes the CPU to vector to the NMI trap routine. When the PWRDN (power down) instruction is executed, the NMI pin must be low in order to force the XC167 into power down mode. If NMI is high, when PWRDN is executed, the part will continue to run in normal mode. If not used, pin NMI should be pulled high externally.					
P6		IO	Port 6 is an 8-bit bidirectional I/O port. Each pin can be programmed for input (output driver in high-impedance state) or output (configurable as push/pull or open drain driver). The input threshold of Port 6 is selectable (standard or special). The Port 6 pins also serve for alternate functions:					
P6.0	7	0	$\frac{110}{CS0}$	Chip Select 0 Output,				
P6.1	8	10 0	CC0IO CS1	CAPCOM1: CC0 Capture Inp./Compare Output Chip Select 1 Output,				
P6.2	9	10 0	CC1IO CS2	CAPCOM1: CC1 Capture Inp./Compare Output Chip Select 2 Output,				
1 0.2		10	CC2IO	CAPCOM1: CC2 Capture Inp./Compare Output				
P6.3	10	0	CS3	Chip Select 3 Output,				
P6.4	11	10 0 10	CC3IO CS4 CC4IO	CAPCOM1: CC3 Capture Inp./Compare Output Chip Select 4 Output, CAPCOM1: CC4 Capture Inp./Compare Output				
P6.5	12		HOLD	External Master Hold Request Input,				
		IO	CC5IO	CAPCOM1: CC5 Capture Inp./Compare Output				
P6.6	13	I/O	HLDA	Hold Acknowledge Output (master mode) or Input (slave mode),				
P6.7	14	10 0 10	CC6IO BREQ CC7IO	CAPCOM1: CC6 Capture Inp./Compare Output Bus Request Output, CAPCOM1: CC7 Capture Inp./Compare Output				



Table 2	Pi	Pin Definitions and Functions (cont'd)							
Sym- bol	Pin Num.	Input Outp.	Function						
P7		IO	Port 7 is a 4-bit bidirectional I/O port. Each pin can be programmed for input (output driver in high-impedance state) or output (configurable as push/pull or open drain driver). The input threshold of Port 7 is selectable (standard or special).						
			Port 7 pins provide inputs/outputs for CAPCOM2 and serial interface lines. ¹⁾						
P7.4	15	I/O I	CC28IO CAPCOM2: CC28 Capture Inp./Compare Outp., CAN2_RxD CAN Node 2 Receive Data Input,						
P7.5	16	 /O	EX7IN Fast External Interrupt 7 Input (alternate pin B) CC29IO CAPCOM2: CC29 Capture Inp./Compare Outp.,						
1 7.0		0	CAN2_TxD CAN Node 2 Transmit Data Output, EX6IN Fast External Interrupt 6 Input (alternate pin B)						
P7.6	17	I/O I	CC30IO CAPCOM2: CC30 Capture Inp./Compare Outp., CAN1_RxD CAN Node 1 Receive Data Input,						
		1	EX7IN Fast External Interrupt 7 Input (alternate pin A)						
P7.7	18	I/O O I	CC31IOCAPCOM2: CC31 Capture Inp./Compare Outp.,CAN1_TxDCAN Node 1 Transmit Data Output,EX6INFast External Interrupt 6 Input (alternate pin A)						



Table 2	Pi	Pin Definitions and Functions (cont'd)								
Sym- bol	Pin Num.	Input Outp.	Function	Function						
P3		IO	Port 3 is a 15-bit bidirectional I/O port. Each pin can be programmed for input (output driver in high-impedance state) or output (configurable as push/pull or open drain driver). The input threshold of Port 3 is selectable (standard or special).							
P3.0	59	 0 	T0IN TxD1 EX1IN	ing Port 3 pins also serve for alternate functions: CAPCOM1 Timer T0 Count Input, ASC1 Clock/Data Output (Async./Sync), Fast External Interrupt 1 Input (alternate pin B)						
P3.1	60	0 I/O I	T6OUT RxD1 EX1IN	GPT2 Timer T6 Toggle Latch Output, ASC1 Data Input (Async.) or Inp./Outp. (Sync.), Fast External Interrupt 1 Input (alternate pin A)						
P3.2	61	I	CAPIN	GPT2 Register CAPREL Capture Input						
P3.3	62	0	T3OUT	GPT1 Timer T3 Toggle Latch Output						
P3.4	63	I	T3EUD	GPT1 Timer T3 External Up/Down Control Input						
P3.5	64	I	T4IN	GPT1 Timer T4 Count/Gate/Reload/Capture Inp						
P3.6	65	I	T3IN	GPT1 Timer T3 Count/Gate Input						
P3.7	66	I	T2IN	GPT1 Timer T2 Count/Gate/Reload/Capture Inp						
P3.8	67	I/O	MRST0	SSC0 Master-Receive/Slave-Transmit In/Out.						
P3.9	68	I/O	MTSR0	SSC0 Master-Transmit/Slave-Receive Out/In.						
P3.10	69	0	TxD0	ASC0 Clock/Data Output (Async./Sync.),						
		I	EX2IN	Fast External Interrupt 2 Input (alternate pin B)						
P3.11	70	I/O I	RxD0 EX2IN	ASC0 Data Input (Async.) or Inp./Outp. (Sync.), Fast External Interrupt 2 Input (alternate pin A)						
P3.12	75	0 0 1	BHE WRH EX3IN	External Memory High Byte Enable Signal, External Memory High Byte Write Strobe, Fast External Interrupt 3 Input (alternate pin B)						
P3.13	76	I/O I	SCLK0 EX3IN	SSC0 Master Clock Output/Slave Clock Input, Fast External Interrupt 3 Input (alternate pin A)						
P3.15	77	0 0	CLKOUT FOUT	Master Clock Output, Programmable Frequency Output						
TCK	71	I	Debug Sys	stem: JTAG Clock Input						
TDI	72	1	Debug Sys	stem: JTAG Data In						
TDO	73	0	Debug Sys	stem: JTAG Data Out						
TMS	74	I	Debug Sys	Debug System: JTAG Test Mode Selection						



0	-		tions and Functions (cont'd)					
Sym-	Pin Num.	Input	Function					
bol	NUM.	Outp.						
P4		IO	Port 4 is an 8-bit bidirectional I/O port. Each pin can be					
			programmed for input (output driver in high-impedance					
			state) or output (configurable as push/pull or open drain					
			driver). The input threshold of Port 4 is selectable (standard or special).					
			Port 4 can be used to output the segment address lines, the					
			optional chip select lines, and for serial interface lines: ¹⁾					
P4.0	80	0	A16 Least Significant Segment Address Line					
P4.1	81	0	A17 Segment Address Line					
P4.2	82	0	A18 Segment Address Line					
P4.3	83	0	A19 Segment Address Line					
P4.4	84	0	A20 Segment Address Line,					
		1	CAN2_RxD CAN Node 2 Receive Data Input,					
		1	EX5IN Fast External Interrupt 5 Input (alternate pin B)					
P4.5	85	0	A21 Segment Address Line,					
		1	CAN1_RxD CAN Node 1 Receive Data Input,					
		1	EX4IN Fast External Interrupt 4 Input (alternate pin B)					
P4.6	86	0	A22 Segment Address Line,					
		0	CAN1_TxD CAN Node 1 Transmit Data Output,					
		1	EX5IN Fast External Interrupt 5 Input (alternate pin A)					
P4.7	87	0	A23 Most Significant Segment Address Line,					
		1	CAN1_RxD CAN Node 1 Receive Data Input,					
		0	CAN2_TxD CAN Node 2 Transmit Data Output,					
		1	EX4IN Fast External Interrupt 4 Input (alternate pin A)					



Table 2	Pi	n Definit	ions and Fu	unctions (cont'd)					
Sym-	Pin	Input	Function						
bol	Num.	Outp.							
PORT1		IO	PORT1 cor	nsists of the two 8-bit bidirectional I/O ports P1L					
			and P1H. E	ach pin can be programmed for input (output					
			driver in hig	h-impedance state) or output.					
			PORT1 is u	used as the 16-bit address bus (A) in					
			demultiplex	ed bus modes (also after switching from a					
			demultiplex	red to a multiplexed bus mode).					
			The following	ng PORT1 pins also serve for alt. functions:					
P1L.0	117	I/O	CC60	CAPCOM6: Input / Output of Channel 0					
P1L.1	118	0	COUT60	CAPCOM6: Output of Channel 0					
P1L.2	119	I/O	CC61	CAPCOM6: Input / Output of Channel 1					
P1L.3	120	0	COUT61						
P1L.4	121	I/O	CC62 CAPCOM6: Input / Output of Channel 2						
P1L.5	122	0	COUT62 CAPCOM6: Output of Channel 2						
P1L.6	123	0	COUT63 Output of 10-bit Compare Channel						
P1L.7	124		CTRAP	CAPCOM2: CC22 Capture Inp./Compare Outp.					
				CTRAP is an input pin with an internal pullup					
				resistor. A low level on this pin switches the					
				CAPCOM6 compare outputs to the logic level					
				defined by software (if enabled).					
	10-	I/O	<u>CC22IO</u>	CAPCOM2: CC22 Capture Inp./Compare Outp.					
P1H.0	127		CC6POS0	CAPCOM6: Position 0 Input,					
			EX0IN	Fast External Interrupt 0 Input (alternate pin B),					
	100	I/O	CC23IO	CAPCOM2: CC23 Capture Inp./Compare Outp.					
P1H.1	128		CC6POS1	CAPCOM6: Position 1 Input,					
	100	I/O	MRST1 SSC1 Master-Receive/Slave-Transmit In/Out.						
P1H.2	129		CC6POS2 CAPCOM6: Position 2 Input,						
	120	1/0	MTSR1	SSC1 Master-Transmit/Slave-Receive Out/Inp.					
P1H.3	130	I/O	SCLK1 SSC1 Master Clock Output / Slave Clock Input,						
P1H.4	131	1 1/0	EX0IN CC24IO	Fast External Interrupt 0 Input (alternate pin A)					
P1H.4 P1H.5	131	1/O 1/O	CC2410 CC2510	CAPCOM2: CC24 Capture Inp./Compare Outp. CAPCOM2: CC25 Capture Inp./Compare Outp.					
P1H.5 P1H.6	132	1/O 1/O	CC25IO CC26IO						
P1H.6 P1H.7				CAPCOM2: CC26 Capture Inp./Compare Outp.					
	134	I/O	CC27IO	CAPCOM2: CC27 Capture Inp./Compare Outp.					



Table 4XC167 Interrupt Nodes (cont'd)

Source of Interrupt or PEC	Control	Vector	Trap
Service Request	Register	Location ¹⁾	Number
ASC1 Autobaud	ASC1_ABIC	xx'0108 _H	42 _H / 66 _D
End of PEC Subchannel	EOPIC	xx'0130 _H	4C _H / 76 _D
CAPCOM6 Timer T12	CCU6_T12IC	xx'0134 _H	4D _H / 77 _D
CAPCOM6 Timer T13	CCU6_T13IC	xx'0138 _H	4E _H / 78 _D
CAPCOM6 Emergency	CCU6_EIC	xx'013C _H	4F _H / 79 _D
CAPCOM6	CAPCOM6	xx'0140 _H	50 _H / 80 _D
SSC1 Transmit	SSC1_TIC	xx'0144 _H	51 _H / 81 _D
SSC1 Receive	SSC1_RIC	xx'0148 _H	52 _H / 82 _D
SSC1 Error	SSC1_EIC	xx'014C _H	53 _H / 83 _D
CAN0	CAN_0IC	xx'0150 _H	54 _H / 84 _D
CAN1	CAN_1IC	xx'0154 _H	55 _H / 85 _D
CAN2	CAN_2IC	xx'0158 _H	56 _H / 86 _D
CAN3	CAN_3IC	xx'015C _H	57 _H / 87 _D
CAN4	CAN_4IC	xx'0164 _H	59 _H / 89 _D
CAN5	CAN_5IC	xx'0168 _H	5A _H / 90 _D
CAN6	CAN_6IC	xx'016C _H	5B _H / 91 _D
CAN7	CAN_7IC	xx'0170 _H	5C _H / 92 _D
RTC	RTC_IC	xx'0174 _H	5D _H / 93 _D
Unassigned node	-	xx'012C _H	3F _H / 63 _D
Unassigned node	-	xx'00FC _H	3F _H / 63 _D
Unassigned node	-	xx'0160 _H	58 _H / 88 _D

 Register VECSEG defines the segment where the vector table is located to. Bitfield VECSC in register CPUCON1 defines the distance between two adjacent vectors. This table

represents the default setting, with a distance of 4 (two words) between two vectors.



3.5 On-Chip Debug Support (OCDS)

The On-Chip Debug Support system provides a broad range of debug and emulation features built into the XC167. The user software running on the XC167 can thus be debugged within the target system environment.

The OCDS is controlled by an external debugging device via the debug interface, consisting of the IEEE-1149-conforming JTAG port and a break interface. The debugger controls the OCDS via a set of dedicated registers accessible via the JTAG interface. Additionally, the OCDS system can be controlled by the CPU, e.g. by a monitor program. An injection interface allows the execution of OCDS-generated instructions by the CPU.

Multiple breakpoints can be triggered by on-chip hardware, by software, or by an external trigger input. Single stepping is supported as well as the injection of arbitrary instructions and read/write access to the complete internal address space. A breakpoint trigger can be answered with a CPU-halt, a monitor call, a data transfer, or/and the activation of an external signal.

Tracing data can be obtained via the JTAG interface or via the external bus interface for increased performance.

The debug interface uses a set of 6 interface signals (4 JTAG lines, 2 break lines) to communicate with external circuitry. These interface signals use dedicated pins.

Complete system emulation is supported by the New Emulation Technology (NET) interface.



3.7 The Capture/Compare Unit CAPCOM6

The CAPCOM6 unit supports generation and control of timing sequences on up to three 16-bit capture/compare channels plus one independent 10-bit compare channel.

In compare mode the CAPCOM6 unit provides two output signals per channel which have inverted polarity and non-overlapping pulse transitions (deadtime control). The compare channel can generate a single PWM output signal and is further used to modulate the capture/compare output signals.

In capture mode the contents of compare timer T12 is stored in the capture registers upon a signal transition at pins CCx.

Compare timers T12 (16-bit) and T13 (10-bit) are free running timers which are clocked by the prescaled system clock.

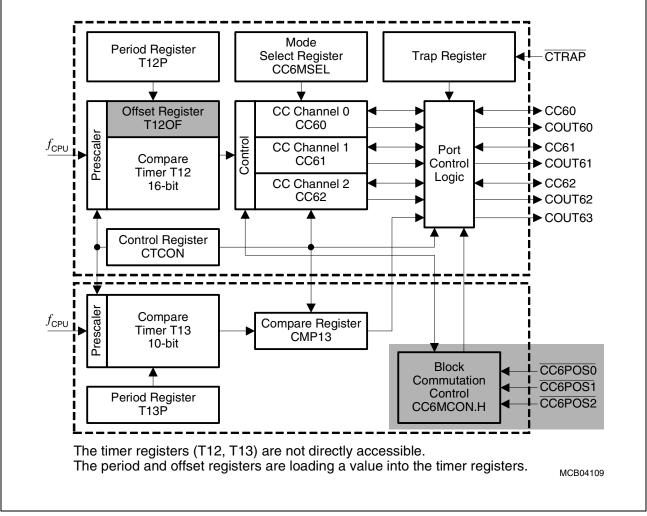


Figure 6 CAPCOM6 Block Diagram

For motor control applications both subunits may generate versatile multichannel PWM signals which are basically either controlled by compare timer T12 or by a typical hall sensor pattern at the interrupt inputs (block commutation).



3.11 Asynchronous/Synchronous Serial Interfaces (ASC0/ASC1)

The Asynchronous/Synchronous Serial Interfaces ASC0/ASC1 (USARTs) provide serial communication with other microcontrollers, processors, terminals or external peripheral components. They are upward compatible with the serial ports of the Infineon 8-bit microcontroller families and support full-duplex asynchronous communication and half-duplex synchronous communication. A dedicated baud rate generator with a fractional divider precisely generates all standard baud rates without oscillator tuning. For transmission, reception, error handling, and baudrate detection 5 separate interrupt vectors are provided.

In asynchronous mode, 8- or 9-bit data frames (with optional parity bit) are transmitted or received, preceded by a start bit and terminated by one or two stop bits. For multiprocessor communication, a mechanism to distinguish address from data bytes has been included (8-bit data plus wake-up bit mode). IrDA data transmissions up to 115.2 kbit/s with fixed or programmable IrDA pulse width are supported.

In synchronous mode, bytes (8 bits) are transmitted or received synchronously to a shift clock which is generated by the ASC0/1. The LSB is always shifted first.

In both modes, transmission and reception of data is FIFO-buffered. An autobaud detection unit allows to detect asynchronous data frames with its baudrate and mode with automatic initialization of the baudrate generator and the mode control bits.

A number of optional hardware error detection capabilities has been included to increase the reliability of data transfers. A parity bit can automatically be generated on transmission or be checked on reception. Framing error detection allows to recognize data frames with missing stop bits. An overrun error will be generated, if the last character received has not been read out of the receive buffer register at the time the reception of a new character is complete.

Summary of Features

- Full-duplex asynchronous operating modes
 - 8- or 9-bit data frames, LSB first, one or two stop bits, parity generation/checking
 - Baudrate from 2.5 Mbit/s to 0.6 bit/s (@ 40 MHz)
 - Multiprocessor mode for automatic address/data byte detection
 - Support for IrDA data transmission/reception up to max. 115.2 kbit/s (@ 40 MHz)
 - Loop-back capability
 - Auto baudrate detection
- Half-duplex 8-bit synchronous operating mode at 5 Mbit/s to 406.9 bit/s (@ 40 MHz)
- Buffered transmitter/receiver with FIFO support (8 entries per direction)
- Loop-back option available for testing purposes
- Interrupt generation on transmitter buffer empty condition, last bit transmitted condition, receive buffer full condition, error condition (frame, parity, overrun error), start and end of an autobaud detection



3.19 Instruction Set Summary

 Table 8 lists the instructions of the XC167 in a condensed way.

The various addressing modes that can be used with a specific instruction, the operation of the instructions, parameters for conditional execution of instructions, and the opcodes for each instruction can be found in the "**Instruction Set Manual**".

This document also provides a detailed description of each instruction.

Mnemonic	Description							
ADD(B)	Add word (byte) operands	2/4						
ADDC(B)	Add word (byte) operands with Carry	2/4						
SUB(B)	Subtract word (byte) operands							
SUBC(B)	Subtract word (byte) operands with Carry							
MUL(U)	L(U) (Un)Signed multiply direct GPR by direct GPR (16- × 16-bit)							
DIV(U)	(Un)Signed divide register MDL by direct GPR (16-/16-bit)	2						
DIVL(U)	(Un)Signed long divide reg. MD by direct GPR (32-/16-bit)	2						
CPL(B)	Complement direct word (byte) GPR	2						
NEG(B)	Negate direct word (byte) GPR	2						
AND(B)	Bitwise AND, (word/byte operands)	2/4						
OR(B)	Bitwise OR, (word/byte operands)	2/4						
XOR(B)	Bitwise exclusive OR, (word/byte operands)	2/4						
BCLR/BSET	Clear/Set direct bit	2						
BMOV(N)	Move (negated) direct bit to direct bit	4						
BAND/BOR/BXOR	AND/OR/XOR direct bit with direct bit	4						
BCMP	Compare direct bit to direct bit	4						
BFLDH/BFLDL	Bitwise modify masked high/low byte of bit-addressable direct word memory with immediate data	4						
CMP(B)	Compare word (byte) operands	2/4						
CMPD1/2	Compare word data to GPR and decrement GPR by 1/2	2/4						
CMPI1/2	Compare word data to GPR and increment GPR by 1/2	2/4						
PRIOR	Determine number of shift cycles to normalize direct word GPR and store result in direct word GPR							
SHL/SHR	Shift left/right direct word GPR	2						

Table 8 Instruction Set Summary



Operating Conditions

The following operating conditions must not be exceeded to ensure correct operation of the XC167. All parameters specified in the following sections refer to these operating conditions, unless otherwise noticed.

Parameter	Symbol	Limi	t Values	Unit	Notes
		Min.	Max.		
Digital supply voltage for the core	V _{DDI}	2.35	2.7	V	Active mode, $f_{CPU} = f_{CPUmax}^{1)2)}$
Digital supply voltage for IO pads	V _{DDP}	4.4	5.5	V	Active mode ²⁾
Supply Voltage Difference	$\Delta V_{\rm DD}$	-0.5	-	V	$V_{\rm DDP}$ - $V_{\rm DDI}^{3)}$
Digital ground voltage	V _{SS}	0		V	Reference voltage
Overload current	I _{OV}	-5	5	mA	Per IO pin ⁴⁾⁵⁾
		-2	5	mA	Per analog input pin ⁴⁾⁵⁾
Overload current coupling	K _{ova}	-	1.0 × 10 ⁻⁴	-	<i>I</i> _{OV} > 0
factor for analog inputs ⁶⁾		-	1.5 × 10 ⁻³	-	<i>I</i> _{OV} < 0
Overload current coupling	K _{OVD}	-	5.0 × 10 ⁻³	-	<i>I</i> _{OV} > 0
factor for digital I/O pins ⁶⁾		_	1.0 × 10 ⁻²	-	I _{OV} < 0
Absolute sum of overload currents	$\Sigma I_{OV} $	-	50	mA	5)
External Load Capacitance	CL	_	50	pF	Pin drivers in default mode ⁷⁾
Ambient temperature	T _A	0	70	°C	SAB-XC167
		-40	85	°C	SAF-XC167
		-40	125	°C	SAK-XC167

Table 10 Operating Condition Parameters

1) f_{CPUmax} = 40 MHz for devices marked ... 40F, f_{CPUmax} = 20 MHz for devices marked ... 20F.

2) External circuitry must guarantee low level at the RSTIN pin at least until both power supply voltages have reached their operating range.

3) This limitation must be fulfilled under all operating conditions including power-ramp-up, power-ramp-down, and power-save modes.



4.2 DC Parameters

Table 11DC Characteristics (Operating Conditions apply)¹⁾

Parameter	Symbol		Limit	Values	Unit	Test Condition
			Min.	Max.		
Input low voltage TTL (all except XTAL1, XTAL3)	V _{IL}	SR	-0.5	0.2 × V _{DDP} - 0.1	V	-
Input low voltage for XTAL1, XTAL3 ²⁾³⁾	V _{ILC}	SR	-0.5	$0.3 imes V_{ m DDI}$	V	-
Input low voltage (Special Threshold)	V _{ILS}	SR	-0.5	$0.45 \times V_{\text{DDP}}$	V	4)
Input high voltage TTL (all except XTAL1, XTAL3)	V _{IH}	SR	0.2 × V _{DDP} + 0.9	V _{DDP} + 0.5	V	-
Input high voltage XTAL1, XTAL3 ²⁾³⁾	V _{IHC}	SR	$0.7 \times V_{\text{DDI}}$	V _{DDI} + 0.5	V	-
Input high voltage (Special Threshold)	V _{IHS}	SR	0.8 × V _{DDP} - 0.2	V _{DDP} + 0.5	V	4)
Input Hysteresis (Special Threshold)	HYS		$0.04 \times V_{\text{DDP}}$	-	V	V_{DDP} in [V], Series resis- tance = 0 $\Omega^{4)}$
Output low voltage	V _{OL}	CC	-	1.0	V	$I_{\rm OL} \leq {I_{\rm OLmax}}^{5)}$
			_	0.45	V	$I_{\rm OL} \leq {I_{\rm OLnom}}^{5)6)}$
Output high voltage ⁷⁾	V _{OH}	CC	V _{DDP} - 1.0	_	V	$I_{\rm OH} \ge I_{\rm OHmax}^{5)}$
			V _{DDP} - 0.45	-	V	$I_{\rm OH} \ge I_{\rm OHnom}^{5)6)}$
Input leakage current (Port 5) ⁸⁾	I _{OZ1}	CC	-	±300	nA	$0 V < V_{IN} < V_{DDP},$ $T_A \le 125 \text{ °C}$
				±200	nA	$0 V < V_{IN} < V_{DDP},$ $T_A \le 85 \ ^{\circ}C^{15)}$
Input leakage current (all other ⁹⁾) ⁸⁾	I _{OZ2}	CC	-	±500	nA	$0.45 V < V_{IN} < V_{DDP}$
Configuration pull-up	$I_{\rm CPUH}^{11)}$		-	-10	μA	$V_{\rm IN} = V_{\rm IHmin}$
current ¹⁰⁾	$I_{\rm CPUL}^{12)}$		-100	_	μA	$V_{\rm IN} = V_{\rm ILmax}$



Parameter	Symbol		Limit	Limit Values		Test Condition
			Min.	Max.		
Configuration pull-	$I_{\rm CPDL}^{11)}$		_	10	μA	$V_{\rm IN} = V_{\rm ILmax}$
down current ¹³⁾	I _{CPDH} ¹²⁾		120	-	μA	$V_{\rm IN} = V_{\rm IHmin}$
Level inactive hold current ¹⁴⁾	<i>I</i> _{LHI} ¹¹⁾		-	-10	μA	$V_{\rm OUT}$ = 0.5 × $V_{\rm DDP}$
Level active hold current ¹⁴⁾	$I_{\rm LHA}^{(12)}$		-100	-	μA	V _{OUT} = 0.45 V
XTAL1, XTAL3 input current	I _{IL}	CC	-	±20	μA	$0 V < V_{IN} < V_{DDI}$
Pin capacitance ¹⁵⁾ (digital inputs/outputs)	C _{IO}	CC	-	10	pF	-

Table 11 DC Characteristics (Operating Conditions apply)¹⁾ (cont'd)

1) Keeping signal levels within the limits specified in this table, ensures operation without overload conditions. For signal levels outside these specifications, also refer to the specification of the overload current I_{OV} .

2) If XTAL1 is driven by a crystal, reaching an amplitude (peak to peak) of $0.4 \times V_{DDI}$ is sufficient.

3) If XTAL3 is driven by a crystal, reaching an amplitude (peak to peak) of $0.25 \times V_{DDI}$ is sufficient.

4) This parameter is tested for P2, P3, P4, P6, P7, P9.

 The maximum deliverable output current of a port driver depends on the selected output driver mode, see Table 12, Current Limits for Port Output Drivers. The limit for pin groups must be respected.

- 6) As a rule, with decreasing output current the output levels approach the respective supply level ($V_{OL} \rightarrow V_{SS}$, $V_{OH} \rightarrow V_{DDP}$). However, only the levels for nominal output currents are guaranteed.
- 7) This specification is not valid for outputs which are switched to open drain mode. In this case the respective output will float and the voltage results from the external circuitry.
- 8) An additional error current (I_{INJ}) will flow if an overload current flows through an adjacent pin. Please refer to the definition of the overload coupling factor K_{OV} .
- 9) The driver of P3.15 is designed for faster switching, because this pin can deliver the reference clock for the bus interface (CLKOUT). The maximum leakage current for P3.15 is, therefore, increased to 1 μA.
- 10) This specification is valid during Reset for configuration on RD, WR, EA, PORT0. The pull-ups on RD and WR (WRL/WRH) are also active during bus hold.
- 11) The maximum current may be drawn while the respective signal line remains inactive.
- 12) The minimum current must be drawn to drive the respective signal line active.
- 13) This specification is valid during Reset for configuration on ALE. The pull-down on ALE is also active during bus hold.
- 14) This specification is valid during Reset for pins P6.4-0, which can act as CS outputs. The pull-ups on CS outputs are also active during bus hold.

The pull-up on pin HLDA is active when arbitration is enabled and the EBC operates in slave mode.

15) Not subject to production test - verified by design/characterization.



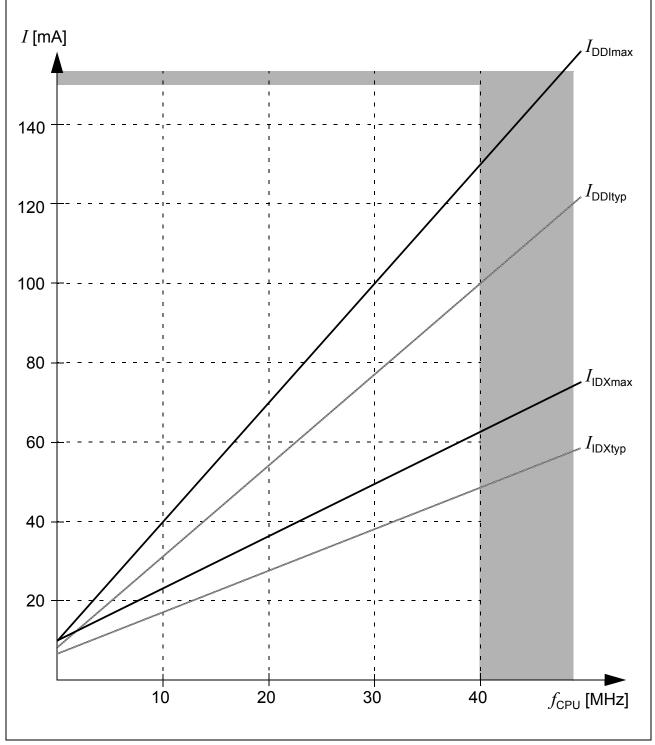


Figure 11 Supply/Idle Current as a Function of Operating Frequency



4.4 AC Parameters

4.4.1 Definition of Internal Timing

The internal operation of the XC167 is controlled by the internal master clock f_{MC} .

The master clock signal $f_{\rm MC}$ can be generated from the oscillator clock signal $f_{\rm OSC}$ via different mechanisms. The duration of master clock periods (TCMs) and their variation (and also the derived external timing) depend on the used mechanism to generate $f_{\rm MC}$. This influence must be regarded when calculating the timings for the XC167.

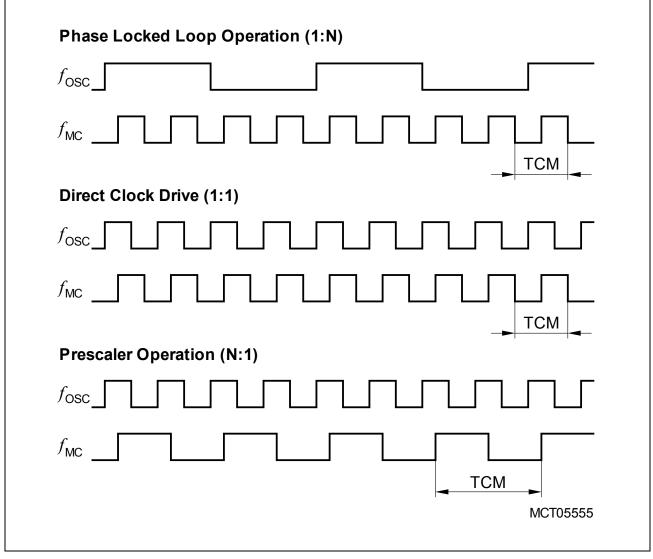


Figure 15 Generation Mechanisms for the Master Clock

Note: The example for PLL operation shown in **Figure 15** refers to a PLL factor of 1:4, the example for prescaler operation refers to a divider factor of 2:1.

The used mechanism to generate the master clock is selected by register PLLCON.



generation or measurement, lower baudrates, etc.) the deviation caused by the PLL jitter is negligible.

The value of the accumulated PLL jitter depends on the number of consecutive VCO output cycles within the respective timeframe. The VCO output clock is divided by the output prescaler (K = PLLODIV+1) to generate the master clock signal f_{MC} . Therefore, the number of VCO cycles can be represented as K × N, where N is the number of consecutive f_{MC} cycles (TCM).

For a period of $\mathbf{N} \times \text{TCM}$ the accumulated PLL jitter is defined by the deviation D_{N} :

 D_N [ns] = ±(1.5 + 6.32 × N / f_{MC}); f_{MC} in [MHz], N = number of consecutive TCMs.

So, for a period of 3 TCMs @ 20 MHz and K = 12: $D_3 = \pm(1.5 + 6.32 \times 3 / 20) = 2.448$ ns.

This formula is applicable for K × N < 95. For longer periods the K × N = 95 value can be used. This steady value can be approximated by: D_{Nmax} [ns] = ±(1.5 + 600 / (K × f_{MC})).

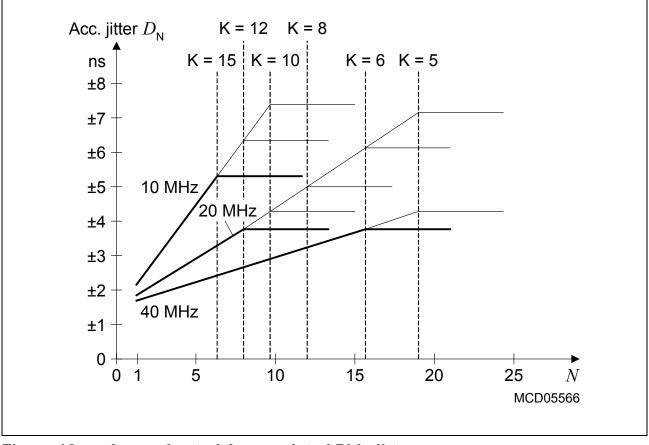


Figure 16 Approximated Accumulated PLL Jitter

Note: The bold lines indicate the minimum accumulated jitter which can be achieved by selecting the maximum possible output prescaler factor K.

Different frequency bands can be selected for the VCO, so the operation of the PLL can be adjusted to a wide range of input and output frequencies:



4.4.4 Testing Waveforms

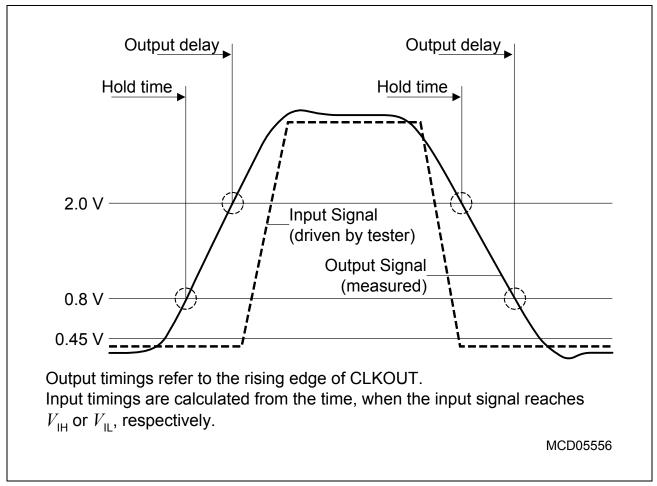


Figure 18 Input Output Waveforms

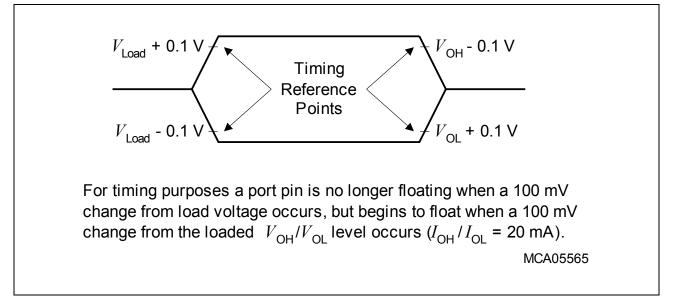


Figure 19 Float Waveforms



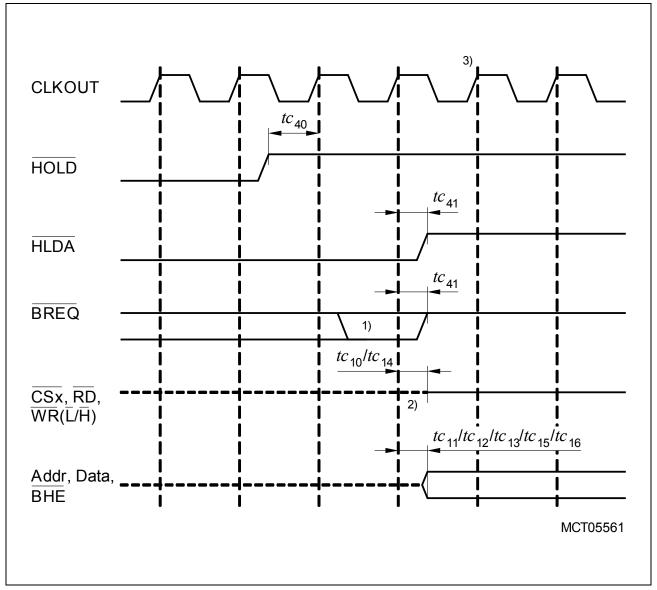


Figure 25 External Bus Arbitration, Regaining the Bus

Notes

- This is the last chance for BREQ to trigger the indicated regain-sequence. Even if BREQ is activated earlier, the regain-sequence is initiated by HOLD going high. Please note that HOLD may also be deactivated without the XC167 requesting the bus.
- 2. The control outputs will be resistive high (pull-up) before being driven inactive (ALE will be low).
- 3. The next XC167 driven bus cycle may start here.